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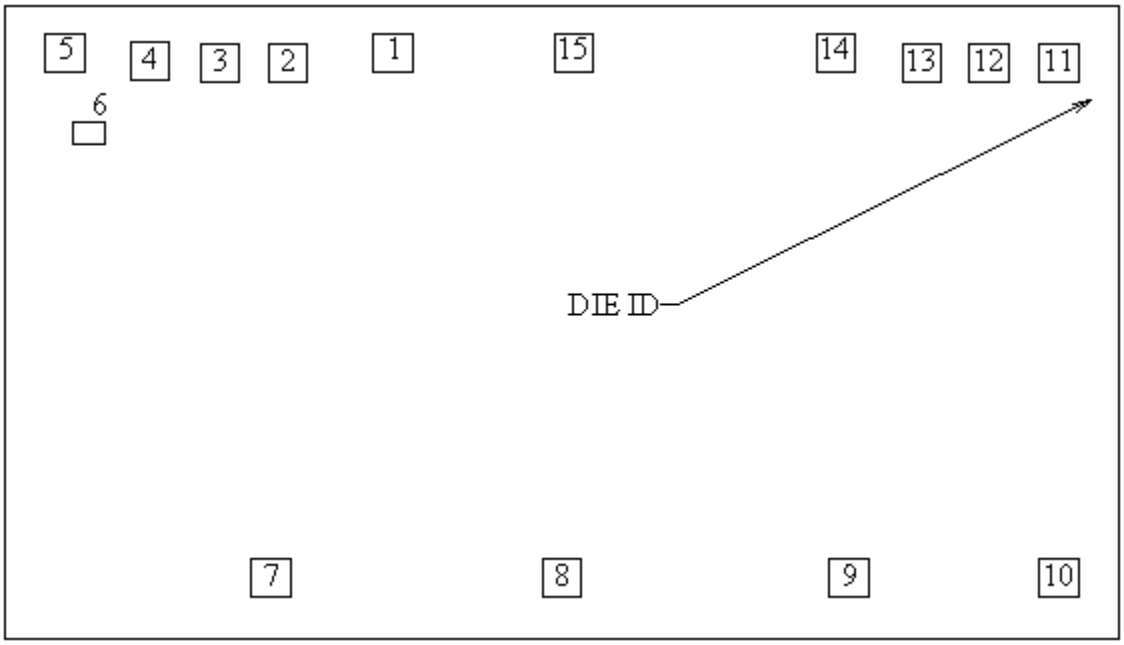
DPBU
Die Datasheet

LF412 MDC MWC
LOW OFFSET, LOW DRIFT DUAL JFET INPUT OPERATIONAL AMPLIFIER

July 19,2004

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LF412B	Bond Pad Opening Size (min)	91μm x 91μm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	2642μm x 1499μm 104.0mils x 59.0mils	Back Side Connection	Floating
Thickness	330μm Nominal		
Min Pitch	498μm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
OUT A	1	-401	639	91	x	91
NC	2	-651	614	90	x	91
NC	3	-813	614	91	x	91
NC	4	-978	619	91	x	91
IN A-	5	-1179	639	91	x	91
NC	6	-1120	450	76	x	53
IN A	7	-691	-605	92	x	91
V-	8	0	-605	92	x	91
IN B+	9	681	-605	92	x	91
IN B-	10	1179	-605	91	x	91
NC	11	1179	614	91	x	91
NC	12	1013	614	91	x	91
NC	13	852	614	90	x	91
OUT B	14	648	639	91	x	91
V+	15	28	639	91	x	91

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